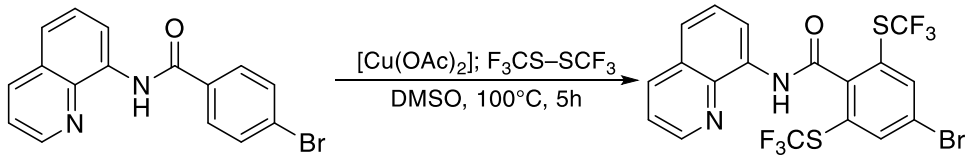
Catalog # 93-2988 Copper(II) acetate, anhydrous, min. 97%

$Cu(OOCCH_3)_2$

Catalysis Applications

Technical Notes:

1. Catalyst for sulfenylation of benzoic acid derivative β-C–H bonds and benzylamine derivative γ-C–H bonds
2. Used in enantio- and regioselective CuH-catalyzed hydroamination of alkenes
3. Used in Cu-catalysed selective hydroamination reactions of alkynes
4. Catalyst for asymmetric hydroamination of unactivated internal olefins to aliphatic amines
5. Catalyst for asymmetric addition of olefin-derived nucleophiles to ketones
6. Catalyst for enantioselective stereodivergent synthesis of amino alcohols
7. Used in highly regio- and enantioselective Cu-catalyzed reductive hydroxymethylation of styrenes and 1,3-dienes with CO_2
8. Used in enantioselective synthesis of trisubstituted allenyl–B(pin) Compounds by phosphine/Cu-catalyzed 1,3-enyne hydroboration
9. Catalyst used in tandem ring-opening/cyclization reactions of cyclopropanols with aryldiazonium salts to generate *N*-arylpyrazoles
10. Used in site-selective Cu-catalyzed azidation of benzylic C−H bonds
11. Catalyst used in proton-directed selective hydroxymethylation of alkynes with CO_2



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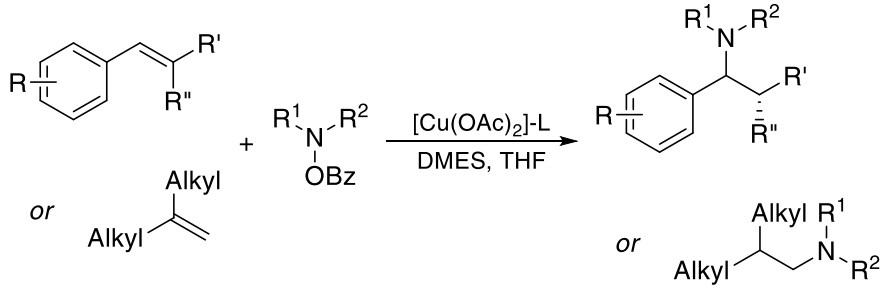

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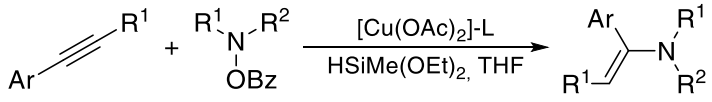

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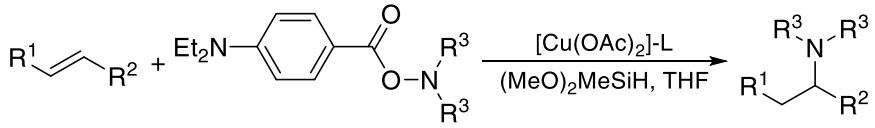

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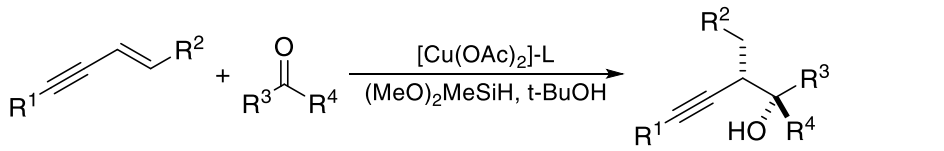

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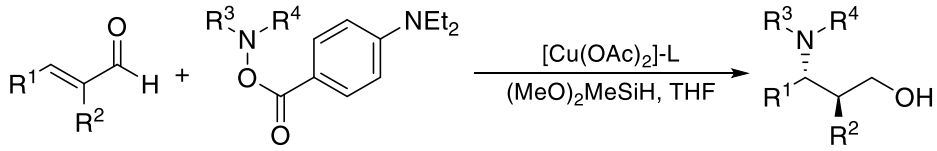

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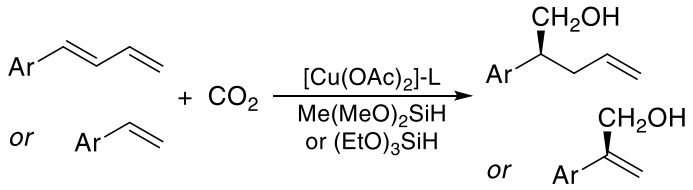

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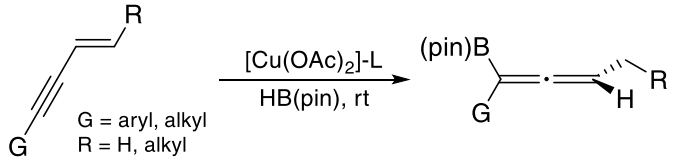

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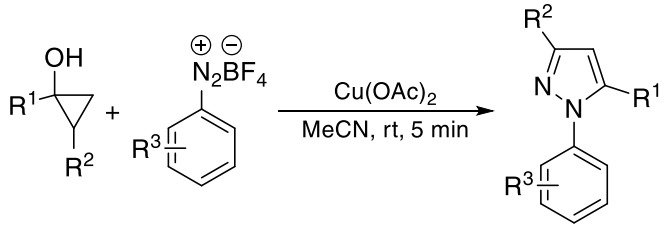

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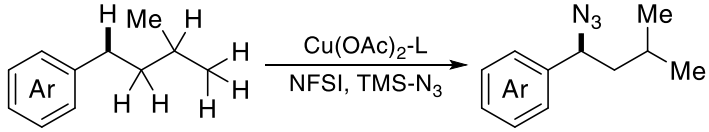

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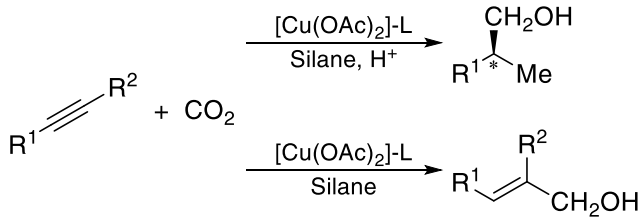

Tech Note (11)
Ref. (11)

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2. *J. Am. Chem. Soc.* **2013**, *135*, 15746
3. *Nat. Chem.* **2015**, *7*, 38
4. *Science* **2015**, *349*, 62
5. *Science* **2016**, *353*, 144
6. *Nature* **2016**, *532*, 353
7. *J. Am. Chem. Soc.* **2017**, *139*, 17011
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CVD/ALD Applications

Thermal Behavior:

- Boiling point: 240°C

Technical Notes:

1. ALD precursor for thin copper film deposition

Target Deposit	Deposition Technique	Delivery Temperature	Pressure	Co-reactants	Deposition Temperature	Ref.
Cu	PE-ALD	138°C	1.7-2.1 Torr	$^{PL}H_2$	85°C	1
Cu_2O	ALD	175 or 185°C	7.5 Torr	H_2O	180-220°C	2

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1. *ECS Transactions*, **2007**, *11*, 67
2. *ACS Omega* **2019**, *4*, 11205